

CLAIMS

1. An electronic device sealing resin sheet,
comprising a first resin layer and a second resin layer,
5 wherein between a marked region obtained after laser
marking is applied to the first resin layer and a region
other than the marked region, a contrast of 20% or more is
shown,

wherein the first resin layer does not comprise
10 filler, and

wherein the first resin layer comprises carbon black,
and the content of the carbon black in the first resin
layer is from 0.1 to 2% by weight.

15 2. The electronic device sealing resin sheet
according to claim 1, wherein the first resin layer
comprises a dye, and

the content of the dye in the first resin layer is
from 0.1 to 2% by weight.

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3. The electronic device sealing resin sheet
according to claim 1 or 2, wherein the second resin layer
is obtained by kneading.

25 4. The electronic device sealing resin sheet
according to any one of the preceding claims, wherein an
etching proportion of the first resin layer is 80% or more.

5. The electronic device sealing resin sheet according to claim 4, wherein the etching proportion of the first resin layer is 100% or more.

5 6. The electronic device sealing resin sheet according to claim 4 or 5, wherein the etching proportion of the first resin layer is 1000% or less.

7. The electronic device sealing resin sheet
10 according to claim 6, wherein the etching proportion of the first resin layer is 800% or less.

8. A method for manufacturing an electronic device package, comprising the step of sealing an electronic
15 device with the electronic device sealing resin sheet recited in any one of claims 1 to 7.

9. The method for manufacturing an electronic device package according to claim 8, comprising the step of
20 applying laser marking to the first resin layer after the electronic device is sealed.